

A device for mounting a substrate includes a susceptor as a support for the substrate to be coated. The susceptor includes an insert whose surface is at least partly formed by a metal carbide layer of a predetermined thickness. The device for mounting the substrate eliminates a contamination of the substrate during processing, such as during production of an epitaxial layer on a wafer. A method for producing the insert includes the steps of producing a metallic preform, embedding the metallic preform in a carbon-containing powder, heating the metallic preform and the carbon-containing powder to an elevated temperature, hard processing the heat-treated preform and disposing the hard-processed preform on the susceptor as an insert.

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